

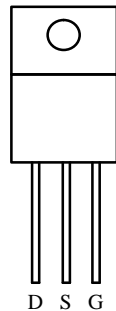
**N-Channel Enhancement-Mode Transistors**

**Product Summary**

$V_{DS}$ (V)	$r_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
200	0.105	27.4

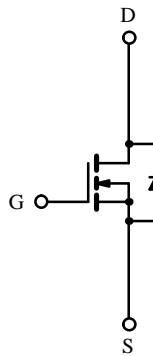
Parametric limits in accordance with MIL-S-19500/592 where applicable.

**TO-254AA  
Hermetic Package**



Top View

Case Isolated



N-Channel MOSFET

**Absolute Maximum Ratings ( $T_C = 25^\circ\text{C}$  Unless Otherwise Noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	200	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ )	$I_D$	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	
Pulsed Drain Current	$I_{DM}$	110	
Avalanche Current	$I_{AR}$	27.4	
Maximum Power Dissipation	$P_D$	150	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

**Thermal Resistance Ratings**

Parameter	Symbol	Limit	Unit
Maximum Junction-to-Case	$R_{thJC}$	0.83	$^\circ\text{C/W}$

Subsequent updates to this data sheet may be obtained via facsimile by calling Siliconix FaxBack, 1-408-970-5600. Please request FaxBack document #1494.

## Specifications (T<sub>J</sub> = 25°C Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ <sup>a</sup>	Max	
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1000 μA	200			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA, T <sub>J</sub> = -55°C			5.0	
		V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA, T <sub>J</sub> = 25°C	2.0		4.0	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V			±100	nA
		V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V, T <sub>J</sub> = 125°C			±200	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 160 V, V <sub>GS</sub> = 0 V			25	μA
		V <sub>DS</sub> = 160 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125°C			250	
		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125°C			1000	
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 27.4 A			0.105	Ω
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 17 A, T <sub>J</sub> = 125°C			0.17	
<b>Dynamic</b>						
Total Gate Charge <sup>c</sup>	Q <sub>g</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 27.5 A	55		115	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>		8		22	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>		30		60	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> = 100 V, R <sub>L</sub> = 3.6 Ω I <sub>D</sub> ≅ 27.4 A, V <sub>GEN</sub> = 10 V, R <sub>G</sub> = 2.35 Ω			35	ns
Rise Time <sup>c</sup>	t <sub>r</sub>				190	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>				170	
Fall Time <sup>c</sup>	t <sub>f</sub>				130	
<b>Source-Drain Diode Ratings and Characteristics</b>						
Continuous Current	I <sub>S</sub>				27.4	A
Pulsed Current	I <sub>SM</sub>				110	
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>F</sub> = 27.4 A, V <sub>GS</sub> = 0 V	0.8		1.9	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 27.4 A, di/dt = 100 A/μs			950	ns

Notes:

- For design aid only; not subject to production testing.
- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
- Independent of operating temperature.